L Number	Hits	Search Text	DB	Time stamp
1	2	(flexible near press) and wafer and (bond or bonding) and (bump or bumps)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:32
2	1	"flexible bladder press" and wafer and (bond or bonding) and (bump or bumps)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:38
3	0	20030148596.URPN.	USPAT	2004/06/23 22:33
4	2	"flexible bladder press" and wafer	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:58
7	8179	press and wafer and bond$3	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:01
8	108	press and (wafer adj bond$3) and (stack or 3-D)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:58
9	525	press and (wafer adj bond$3)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:40
10	231	press and (wafer adj bond$3) and (stack or 3-D or dimensional)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:41
11	0	(press and (wafer adj bond$3) and (stack or 3-D)) and (flexible near press)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:41
12	1	(press and (wafer adj bond$3) and (stack or 3-D)) and (bladder near press)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:41
13	7	(press and wafer and bond$3) and (bladder near press)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:57
14	18	(press and wafer and bond$3) and (pressure near bladder)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:57

15	29210	pressure and wafer and bond$3	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:57
17	420	pressure and (wafer adj bond$3) and (stack or 3-D)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:58
18	0	(pressure and (wafer adj bond$3) and (stack or 3-D)) and (pressure near bladder)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:58
19	0	"flexible pressure bladder" and wafer	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/23 22:59
21	307	autoclave and wafer and bonding	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 00:31
22	277	(autoclave and wafer and bonding) and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 00:11
16	55	(pressure and wafer and bond$3) and (pressure near bladder)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 00:12
23	0	6475357.URPN.	USPAT	2004/06/24 00:20
24	3	("5429733" | "5447615" | "6080050").PN.	USPAT	2004/06/24 00:20
25	0	6197665.URPN.	USPAT	2004/06/24 00:22
26	6	("5090246" | "5148265" | "5148266" | "5227812" | "5282312" | "5398863").PN.	USPAT	2004/06/24 00:22
20	79	"pressure bladder" and wafer	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 00:28
27	30	("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 00:31
28	307	(autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 00:58
29	0	20030027373.URPN.	USPAT	2004/06/24 00:33

30	9	vertical adj stack adj integration	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 00:58
31	8	(vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:02
32	1337	wafer$4wafer	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:01
33	241	wafer$4wafer and stack	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:02
34	26	wafer$4wafer and stack near vertical	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:02
35	17	(wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:22
36	508	438/51	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:21
37	16	438/51 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:21
38	16	(438/51 and (bond or bonding) and wafer and stack and pressure) not ((wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder)))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:12
39	686	438/52	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:23
40	25	438/52 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:23

41	19	(438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:23
42	612	438/53	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:24
43	20	438/53 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:24
44	12	(438/53 and (bond or bonding) and wafer and stack and pressure) not (438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:24
45	2947	438/106	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:43
46	62	438/106 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:43
47	56	(438/106 and (bond or bonding) and wafer and stack and pressure) not (438/53 and (bond or bonding) and wafer and stack and pressure) not (438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:44
48	0	6632706.URPN.	USPAT	2004/06/24 01:33
49	42	("4070230" | "4131985" | "4416054" | "4539068" | "4585991" | "4612083" | "4617160" | "4618397" | "4618763" | "4702936" | "4706166" | "4721938" | "4761681" | "4784721" | "5070026" | "5071510" | "5130894" | "5236118" | "5262351" | "5270261" | "5273940" | "5284796" | "5324687" | "5385632" | "5424920" | "5426072" | "5432729" | "5457879" | "5489554" | "5502667" | "5534465" | "5563084" | "5581498" | "5637536" | "5656552" | "5694588" | "5760478" | "5793115" | "5880010" | "5902118" | "6194245" | "6208545").PN.	USPAT	2004/06/24 01:33

50	1642	438/107	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:47
51	71	438/107 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:47
52	43	(438/107 and (bond or bonding) and wafer and stack and pressure) not (438/106 and (bond or bonding) and wafer and stack and pressure) not (438/53 and (bond or bonding) and wafer and stack and pressure) not (438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:48
53	892	438/109	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:53
54	69	438/109 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:54
55	41	(438/109 and (bond or bonding) and wafer and stack and pressure) not (438/107 and (bond or bonding) and wafer and stack and pressure) not (438/106 and (bond or bonding) and wafer and stack and pressure) not (438/53 and (bond or bonding) and wafer and stack and pressure) not (438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:54
56	1250	438/455	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:58
57	110	438/455 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:58

58	72	(438/455 and (bond or bonding) and wafer and stack and pressure) not (438/109 and (bond or bonding) and wafer and stack and pressure) not (438/107 and (bond or bonding) and wafer and stack and pressure) not (438/106 and (bond or bonding) and wafer and stack and pressure) not (438/53 and (bond or bonding) and wafer and stack and pressure) not (438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:58
59	333	438/456	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:59
60	27	438/456 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:59
61	3	(438/456 and (bond or bonding) and wafer and stack and pressure) not (438/455 and (bond or bonding) and wafer and stack and pressure) not (438/109 and (bond or bonding) and wafer and stack and pressure) not (438/107 and (bond or bonding) and wafer and stack and pressure) not (438/106 and (bond or bonding) and wafer and stack and pressure) not (438/53 and (bond or bonding) and wafer and stack and pressure) not (438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:59
62	138	438/457	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:59
63	11	438/457 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:59

64	0	(438/457 and (bond or bonding) and wafer and stack and pressure) not (438/456 and (bond or bonding) and wafer and stack and pressure) not (438/455 and (bond or bonding) and wafer and stack and pressure) not (438/109 and (bond or bonding) and wafer and stack and pressure) not (438/107 and (bond or bonding) and wafer and stack and pressure) not (438/106 and (bond or bonding) and wafer and stack and pressure) not (438/53 and (bond or bonding) and wafer and stack and pressure) not (438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:59
65	1038	438/459	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:00
66	60	438/459 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:00
67	15	(438/459 and (bond or bonding) and wafer and stack and pressure) not (438/457 and (bond or bonding) and wafer and stack and pressure) not (438/456 and (bond or bonding) and wafer and stack and pressure) not (438/455 and (bond or bonding) and wafer and stack and pressure) not (438/109 and (bond or bonding) and wafer and stack and pressure) not (438/107 and (bond or bonding) and wafer and stack and pressure) not (438/106 and (bond or bonding) and wafer and stack and pressure) not (438/53 and (bond or bonding) and wafer and stack and pressure) not (438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:01
68	454	438/975	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:01
69	4	438/975 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:02

70	3	(438/975 and (bond or bonding) and wafer and stack and pressure) not (438/459 and (bond or bonding) and wafer and stack and pressure) not (438/457 and (bond or bonding) and wafer and stack and pressure) not (438/456 and (bond or bonding) and wafer and stack and pressure) not (438/455 and (bond or bonding) and wafer and stack and pressure) not (438/109 and (bond or bonding) and wafer and stack and pressure) not (438/107 and (bond or bonding) and wafer and stack and pressure) not (438/106 and (bond or bonding) and wafer and stack and pressure) not (438/53 and (bond or bonding) and wafer and stack and pressure) not (438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:02
71	704	438/977	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:01
72	32	438/977 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:02
73	4	(438/977 and (bond or bonding) and wafer and stack and pressure) not (438/975 and (bond or bonding) and wafer and stack and pressure) not (438/459 and (bond or bonding) and wafer and stack and pressure) not (438/457 and (bond or bonding) and wafer and stack and pressure) not (438/456 and (bond or bonding) and wafer and stack and pressure) not (438/455 and (bond or bonding) and wafer and stack and pressure) not (438/109 and (bond or bonding) and wafer and stack and pressure) not (438/107 and (bond or bonding) and wafer and stack and pressure) not (438/106 and (bond or bonding) and wafer and stack and pressure) not (438/53 and (bond or bonding) and wafer and stack and pressure) not (438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:02